

ABSTRACT

INTERNAL CRACK DETECTING METHOD AND INTERNAL CRACK DETECTING APPARATUS

Disclosed herein is an internal crack detecting method for detecting an internal crack in a wafer. The internal crack detecting method includes a first image recording step of applying near infrared light having a transmission wavelength to a reference wafer having the same configuration as the wafer as a target wafer to be subjected to the detection of the internal crack, thereby obtaining a first image of the reference wafer having no internal crack and then recording the first image, a processing step of processing the target wafer, a second image recording step of applying the near infrared light to the target wafer, thereby obtaining a second image of the target wafer processed and then recording the second image, and an internal crack detecting step of removing the same image information between the first image and the second image from the second image to obtain a residual image, thereby detecting the residual image as the internal crack in the target wafer.

(Figure 6B)